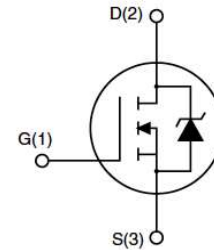


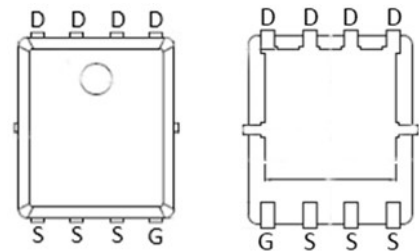
### Features

- 60V,160A  
 $R_{DS(on)} < 2.9m\Omega @ V_{GS}=10V$  TYP:2.4m $\Omega$   
 $R_{DS(on)} < 3.6m\Omega @ V_{GS}=4.5V$  TYP:3.0m $\Omega$
- Super Trench
- Extremely low on-resistance RDS(on)
- Excellent Qg x RDS(on) product(FOM)
- Qualified according to JEDEC criteria



### Applications

- Synchronous Rectification for AC/DC Quick Charger
- Battery management
- UPS (Uninterruptible Power Supplies)



PDFN5X6

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G029N06G	APG029N06G	PDFN5X6	-	-	5000

### ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Silicon Limited)	I <sub>D</sub>	T <sub>c</sub> =25°C	160
		T <sub>c</sub> =100°C	101
Continuous Drain Current (Package Limited) T <sub>c</sub> =25°C		80	A
Pulsed Drain Current	I <sub>DM</sub>	640	A
Single Pulsed Avalanche Energy (T <sub>c</sub> =25°C, L=0.3mH) <sup>(2)</sup>	E <sub>AS</sub>	189	mJ
Drain Power Dissipation	P <sub>D</sub>	113	W
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	1.11	°C/W
Thermal Resistance- Junction to Ambient	R <sub>θJA</sub>	56	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C

MOSFET ELECTRICAL CHARACTERISTICS( $T_J=25^\circ\text{C}$  unless otherwise noted)

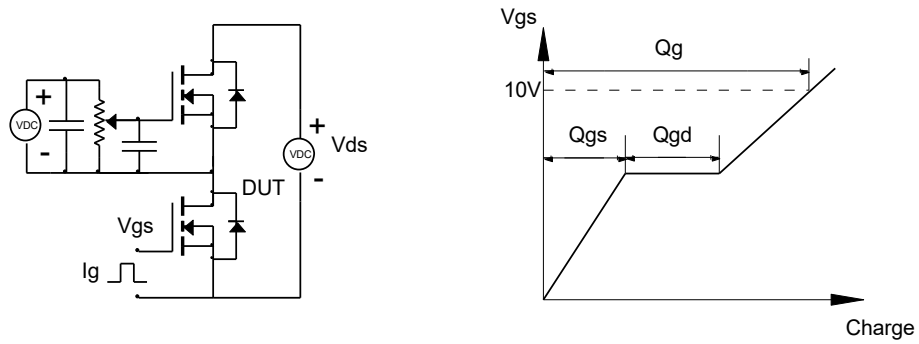
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 60V, V_{GS} = 0V$	-	0.02	1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	$\pm 10$	$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	-	2.2	V
Drain-source on-resistance <sup>(a)</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 40A$	-	2.4	2.9	m $\Omega$
		$V_{GS} = 4.5V, I_D = 32A$		3.0	3.6	m $\Omega$
Gate Resistance	Rg	$V_{GS}=0V, V_{DS}$ Open, f=1MHz		0.93		$\Omega$
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 30V, V_{GS} = 0V, f = 1.0MHz$	-	4610	6915	pF
Output Capacitance	$C_{oss}$		-	2188	3282	
Reverse Transfer Capacitance	$C_{rss}$		-	66	132	
<b>Switching characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD}=30V, I_D=40A, R_G=2.7\Omega,$ $V_G=10V$	-	14.1	-	ns
Turn-on rise time	$t_r$		-	63.7	-	
Turn-off delay time	$t_{d(off)}$		-	46.8	-	
Turn-off fall time	$t_f$		-	105.1	-	
Total Gate Charge	Qg	$V_{DS}=30V, I_D=40A,$ $V_{GS}=10V$	-	74.4	111.6	nC
Gate-Source Charge	Qgs		-	17.3	-	
Gate-Drain Charge	Qgd		-	9.5	18.9	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(a)</sup>	$V_{SD}$	$T_J=25^\circ\text{C}, V_{GS} = 0V, I_S=40A$	-	0/82	1.23	V
Diode Forward current	$I_S$	$T_C=25^\circ\text{C}$	-	-	160	A
Body Diode Reverse Recovery Time	trr	$T_J=25^\circ\text{C}, I_F=40A, di/dt=300A/us$		52.8	105.6	ns
Body Diode Reverse Recovery Charge	Qrr	$T_J=25^\circ\text{C}, I_F=440A, di/dt=300A/us$		253	56.3	nc

**Notes:**

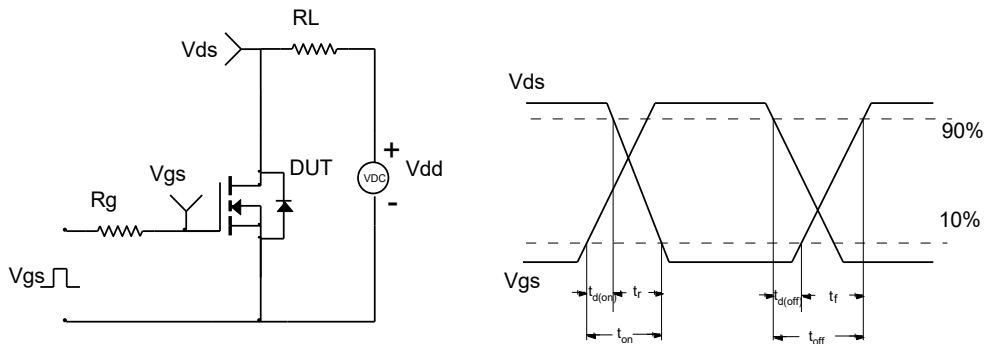
- a) Pulse width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$   
b) Guaranteed by design, not subject to production testing

**Test Circuit**

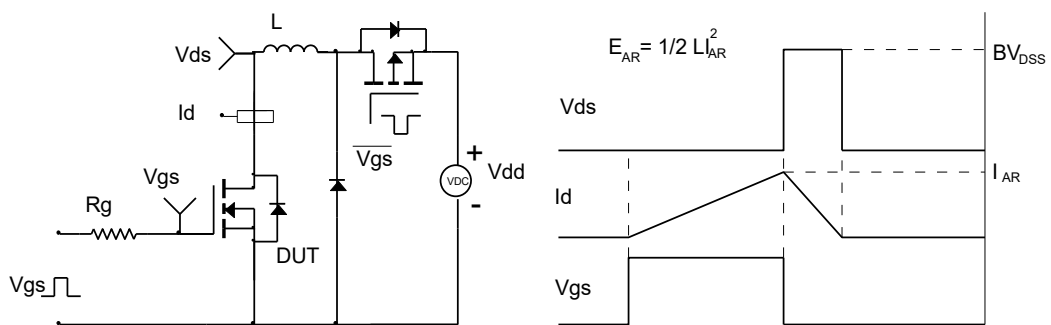
Gate Charge Test Circuit & Waveform



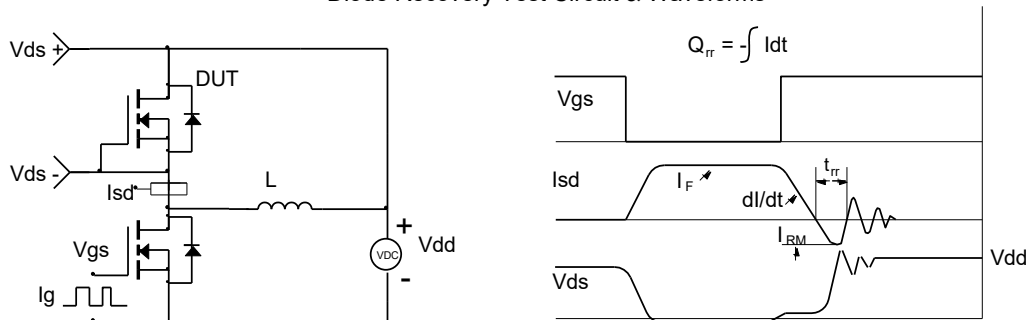
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



**Typical Performance Characteristics**

Fig 1: Output Characteristics

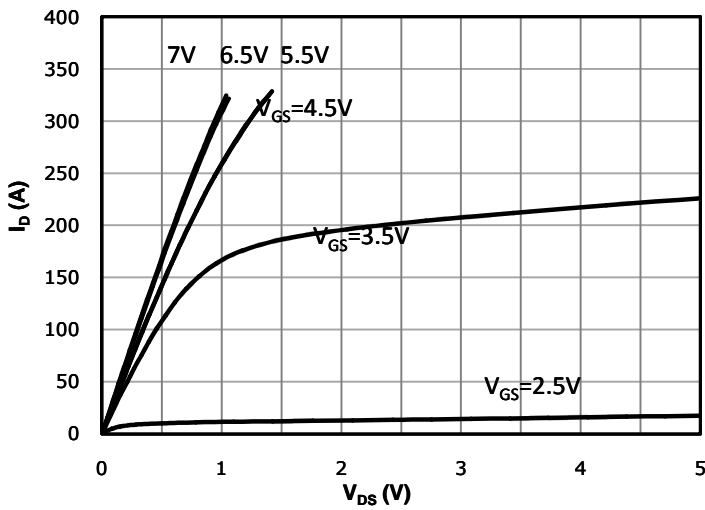


Fig 2: Transfer Characteristics

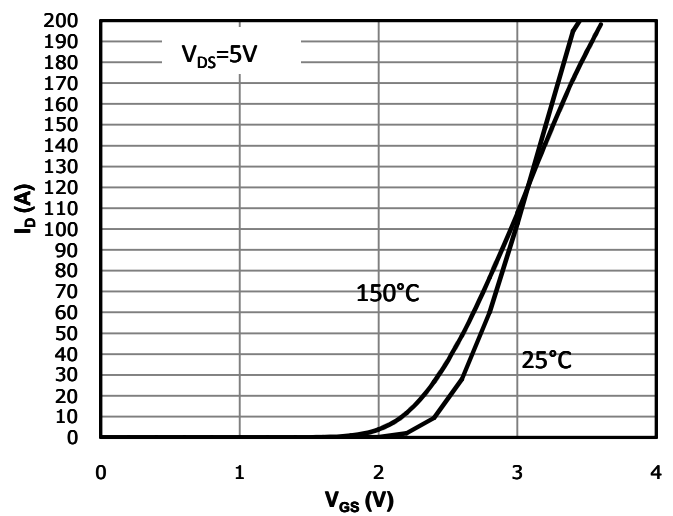


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

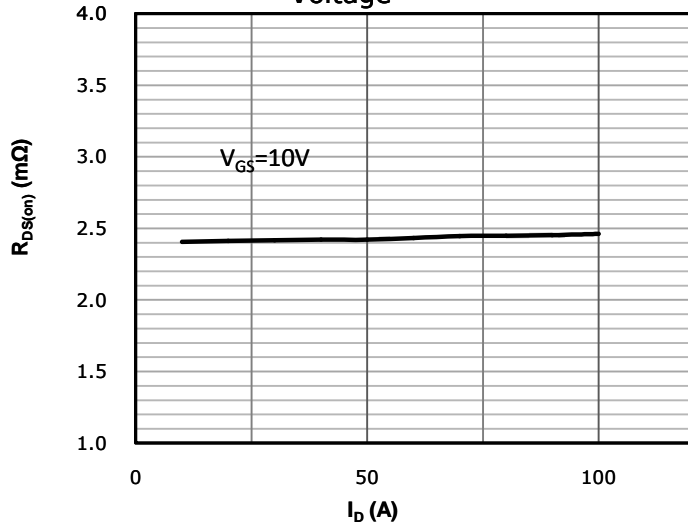


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

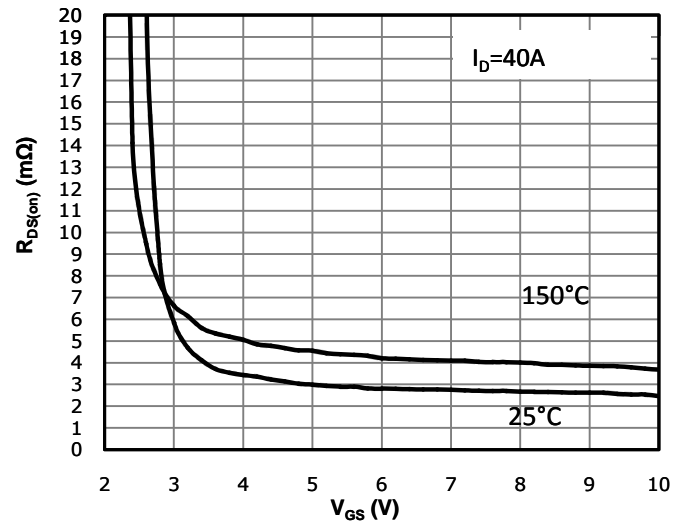


Fig 5:  $R_{DS(on)}$  vs. Temperature

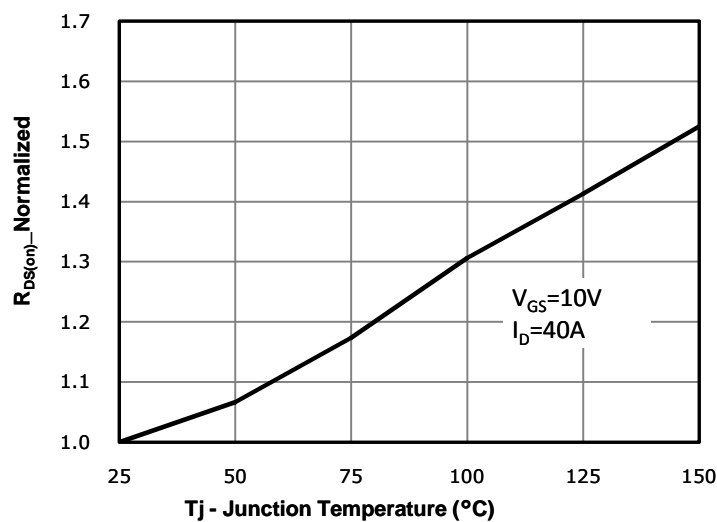
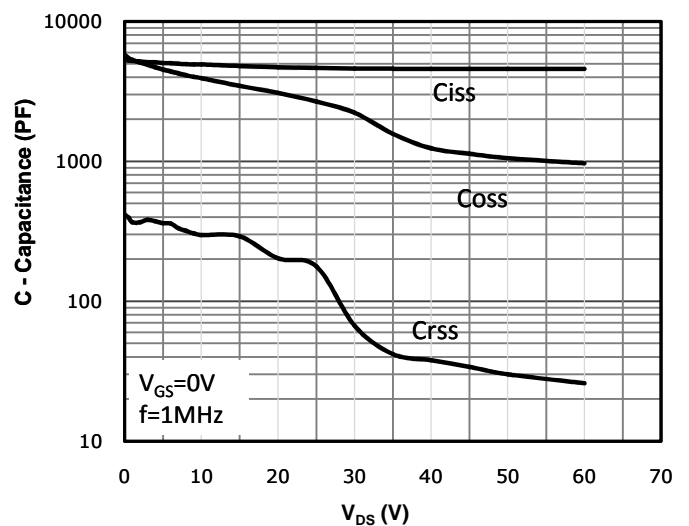


Fig 6: Capacitance Characteristics



**Typical Performance Characteristics**

Fig 7: Gate Charge Characteristics

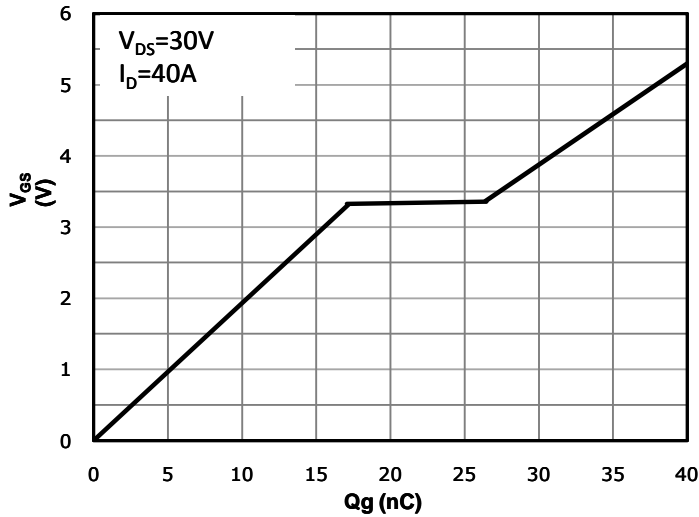


Fig 8: Body-diode Forward Characteristics

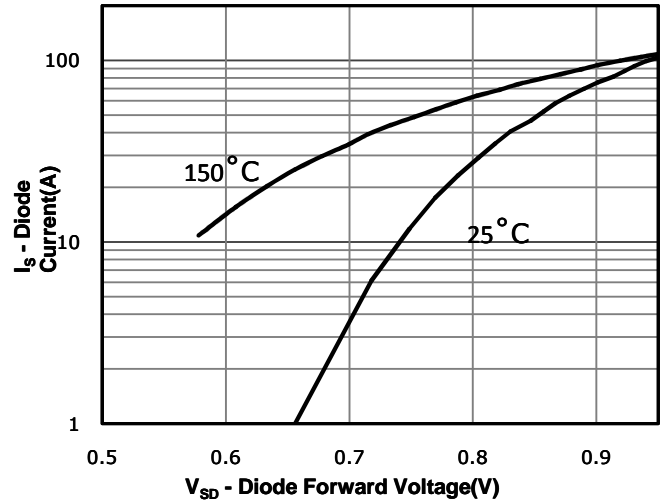


Fig 9: Power Dissipation

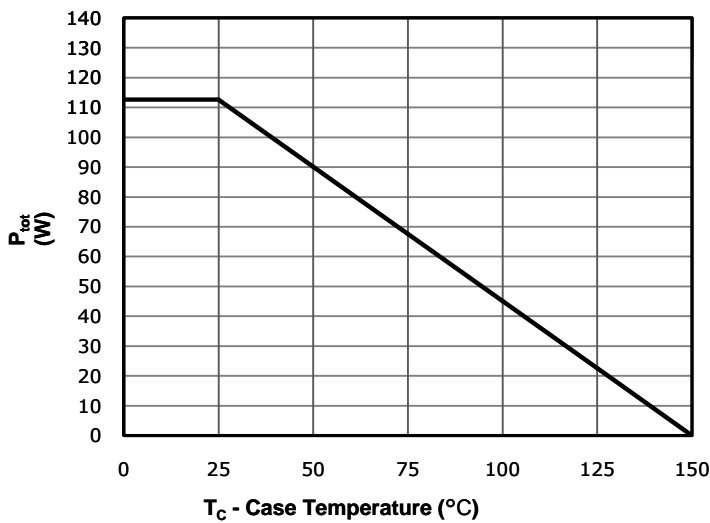


Fig 10: Drain Current Derating

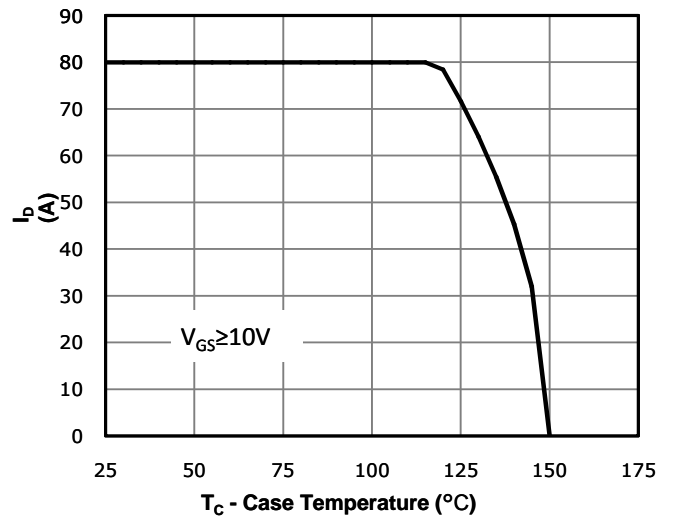
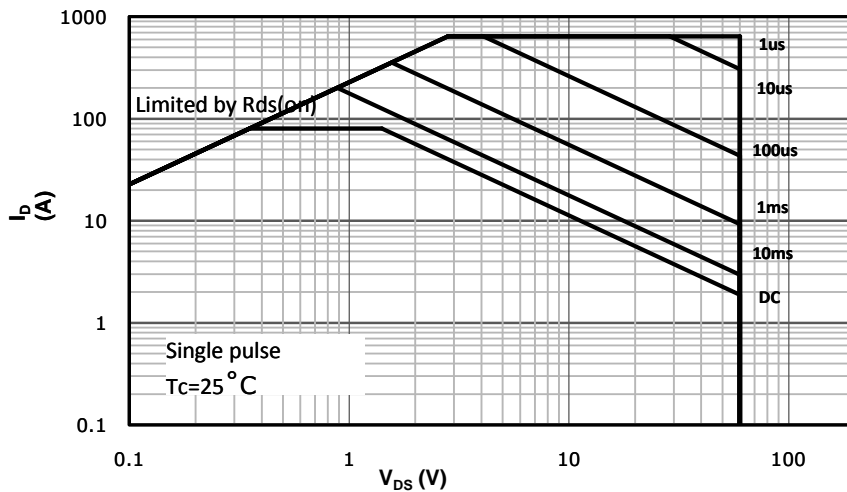
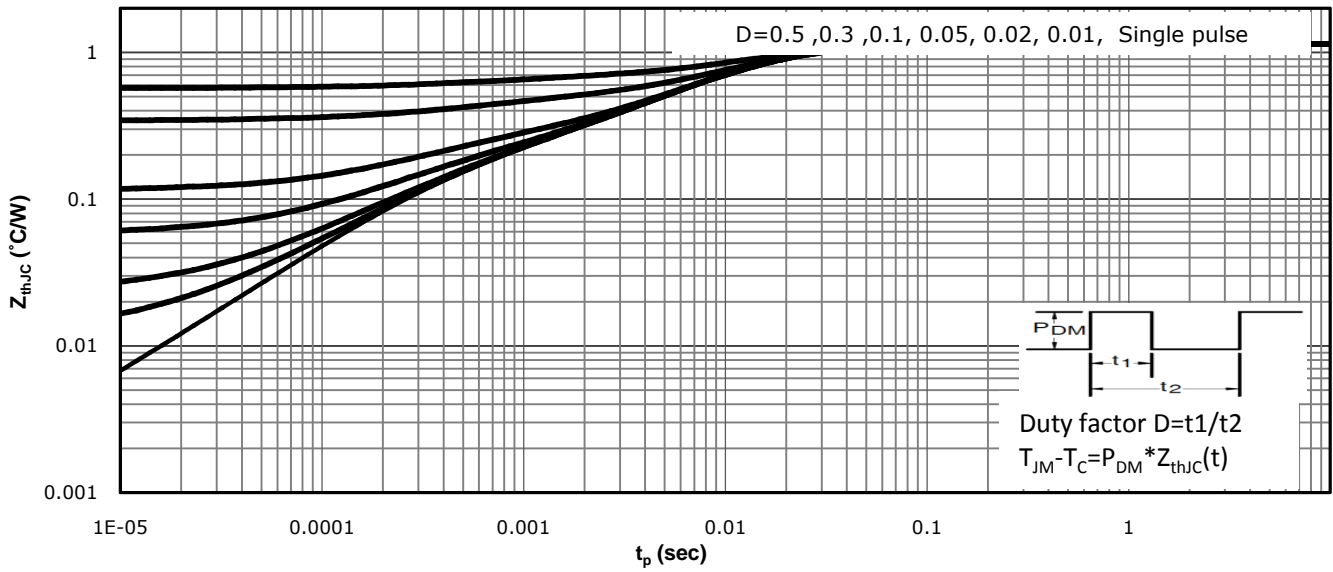


Fig 11: Safe Operating Area

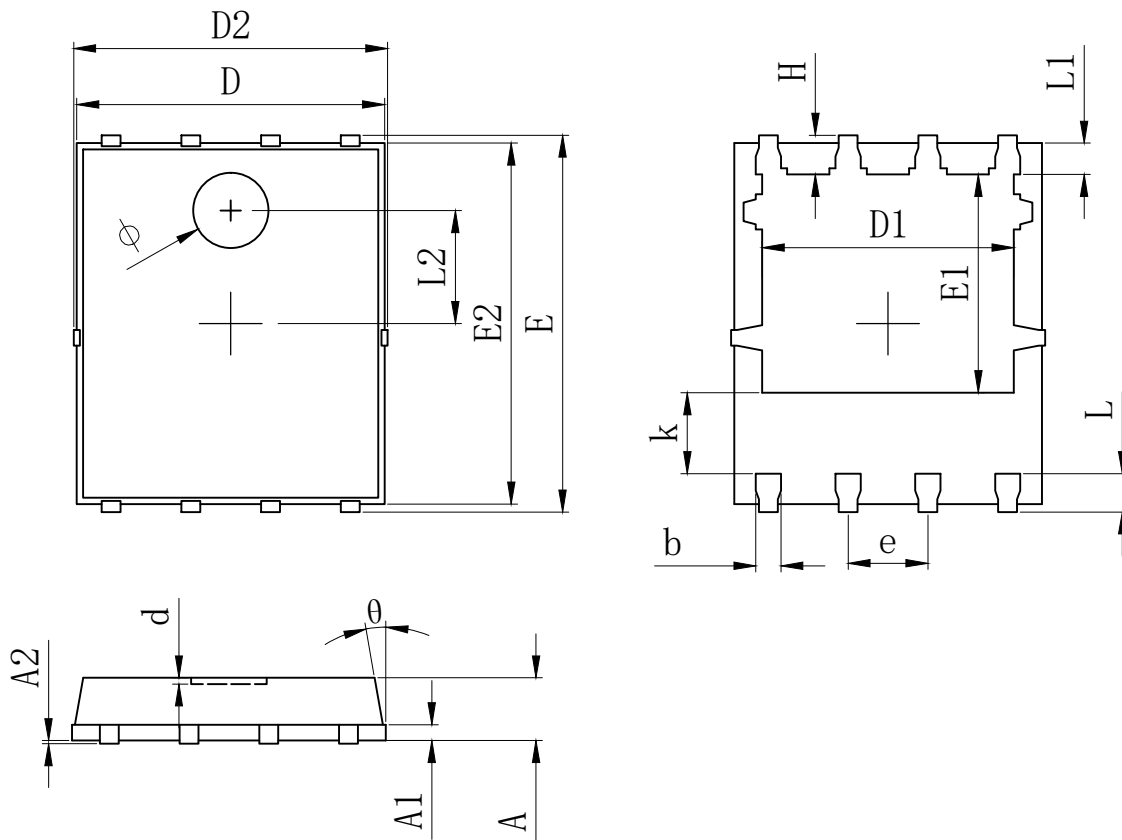


**Typical Performance Characteristics**

Fig 12: Max. Transient Thermal Impedance



**PDFN5X6 Package Information**



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
$\theta$	8°	10°	12°
$\phi$	1.100	1.200	1.300
d			0.100

## Revision History

Revision	Release	Remark
V1.0	2023/05/17	Initial Release

## Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.